

ABSTRACT OF THE DISCLOSURE

A vertically mountable semiconductor device including a plurality of bond pads disposed proximate to a single edge thereof. The bond pads are bumped with an electrically conductive material. The semiconductor device may also include a support member. Alternatively, the semiconductor device may be laminated to one or more adjacent semiconductor devices. The present invention also includes a method of attaching the semiconductor device to a carrier substrate. Preferably, solder paste is applied to terminals on the carrier substrate. The semiconductor device is oriented vertically over the carrier substrate, such that the bumped bond pads align with their corresponding terminals. The bumps are placed into contact with the solder paste. The bumps and solder paste are then fused to form a joint between each of the bond pads and its respective terminal, establishing an electrically conductive connection therebetween and imparting structural stability to the semiconductor device.

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